

Surface Mount Schottky Barrier Rectifier

Reverse Voltage - 20 to 200 V Forward Current - 5.0A

Features

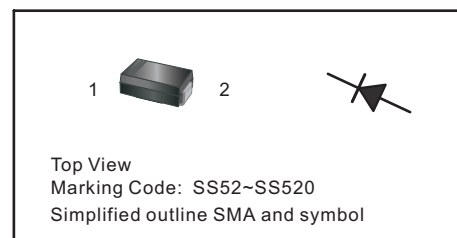
- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 60mg / 0.0021oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS52G	SS54G	SS56G	SS58G	SS510G	SS512G	SS515G	SS520G	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	5.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	120				100				A
Max Instantaneous Forward Voltage at 5 A	V _F	0.55		0.70		0.85				V
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a = 100°C	I _R	1.0 50								mA
Typical Junction Capacitance ⁽¹⁾	C _j	500		300						pF
Typical Thermal Resistance ⁽²⁾	R _{θJA}	60								°C/W
Operating Junction Temperature Range	T _j	-55 ~ +150								°C
Storage Temperature Range	T _{stg}	-55 ~ +150								°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C (2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

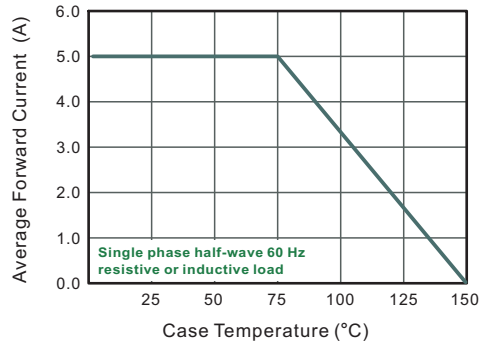


Fig.2 Typical Reverse Characteristics

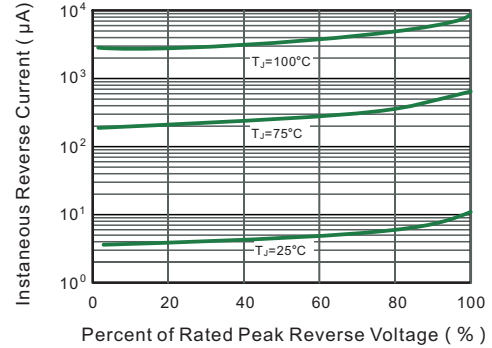


Fig.3 Typical Forward Characteristic

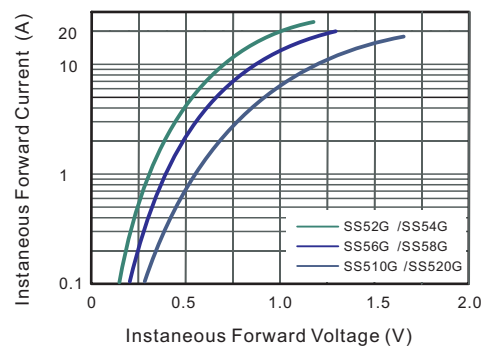


Fig.4 Typical Junction Capacitance

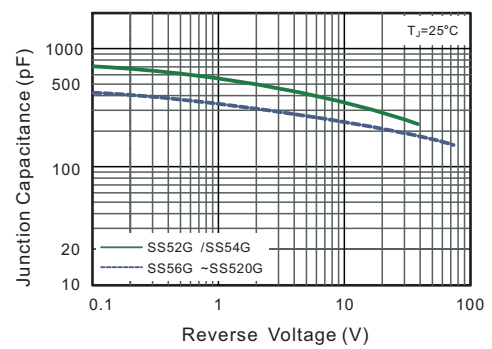


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

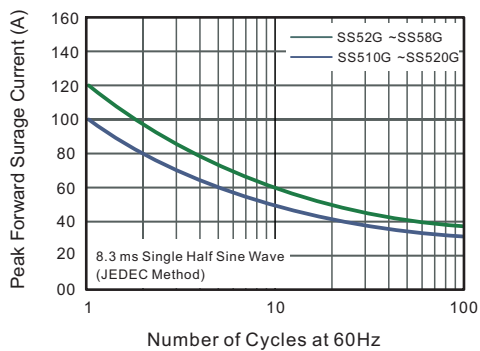
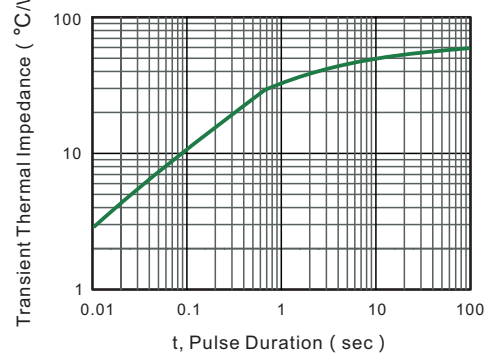


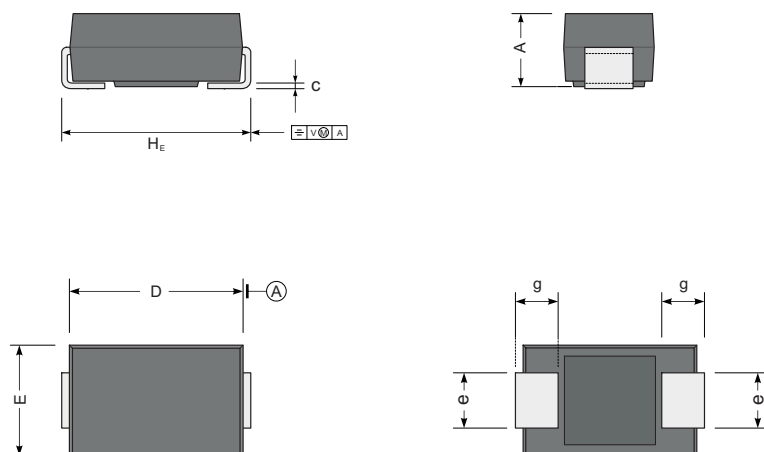
Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

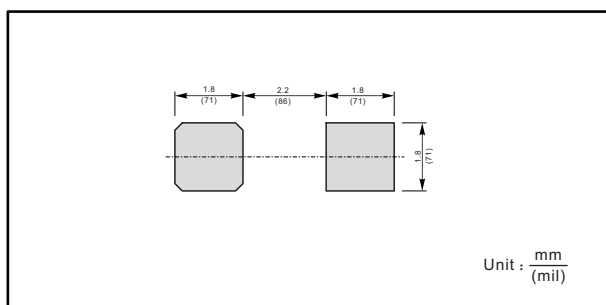
Plastic surface mounted package; 2 leads

SMA



UNIT		A	D	E	H _E	c	e	g
mm	max	2.2	4.83	2.9	5.4	0.31	1.7	1.5
	min	1.9	4.32	2.3	4.7	0.12	1.2	0.9
mil	max	87	190	114	213	12	67	59
	min	75	170	91	185	5	47	35

The recommended mounting pad size



Marking

Type number	Marking code
SS52G	SS52
SS54G	SS54
SS56G	SS56
SS58G	SS58
SS510G	SS510
SS512G	SS512
SS515G	SS515
SS520G	SS520